

**SOCKET APPARATUS PARTICULARLY ADAPTED FOR BGA TYPE
SEMICONDUCTOR DEVICES**

Abstract of the Disclosure

A socket (1) for removably receiving semiconductor devices (8) for testing purposes has film contacts (81) each having a continuous or discontinuous annulus (71, 73, 76, 78) that has been formed on a film substrate and with a recess (72, 74, 77, 79) formed within the annulus exposed at a bottom of a seating or accommodating portion (31). When a BGA type semiconductor device (8) is received in the accommodating part (31) and a cover (16) is closed, electrically conductive balls (9) on the bottom of the semiconductor device (8) are pressed against respective film annular contacts (81, 82, 83, 84) thereby effecting an electric connection. Since the bottom most portion of the electrically conductive balls (9) are located within the recesses of the annular contacts, they will not be deformed. Since the film contacts (81) are prepared by etching and plating, the pitch can be easily narrowed, or otherwise modified.

Figure 2